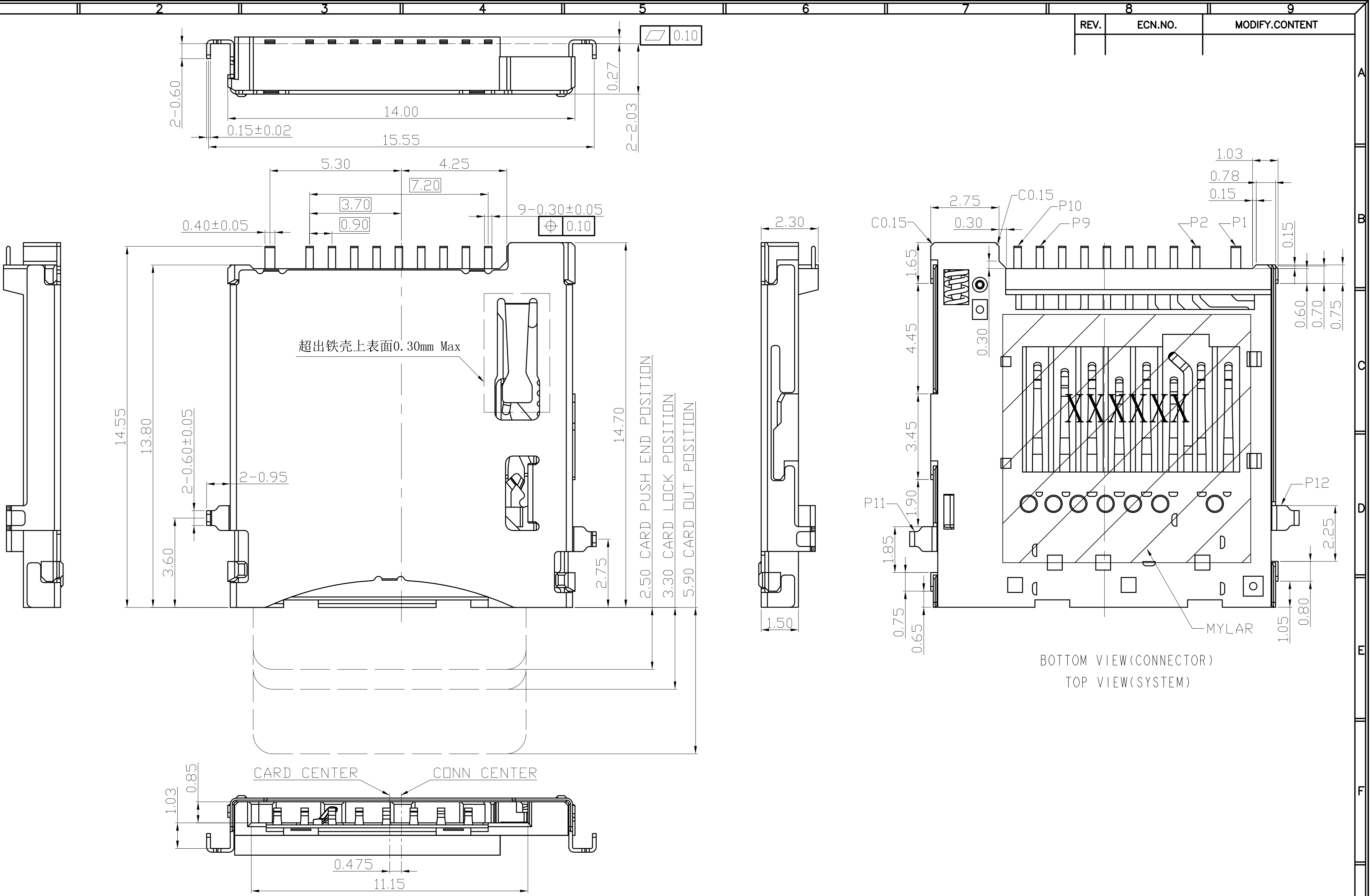
REV.	ECN.NO.	MODIFY.CONTENT



GENERAL	TOLERANCE	DWG.NO.	MR198-AP401-00	PART.NO.	MR198-AP401-✱✱	DRAWN	L.M.J 2019.07.19	UNIT	mm	SCALE	1:1
x.±0.50	x.°± 5°	REV.	A	TITLE	Micro SD Push反向沉板2.03 conn.	CHECKED					
.x±0.25	.x°± 2°	SIZE									
.xx±0.15	.xx°± 1°	A4		SHEET	1 OF 3	APPROVED					

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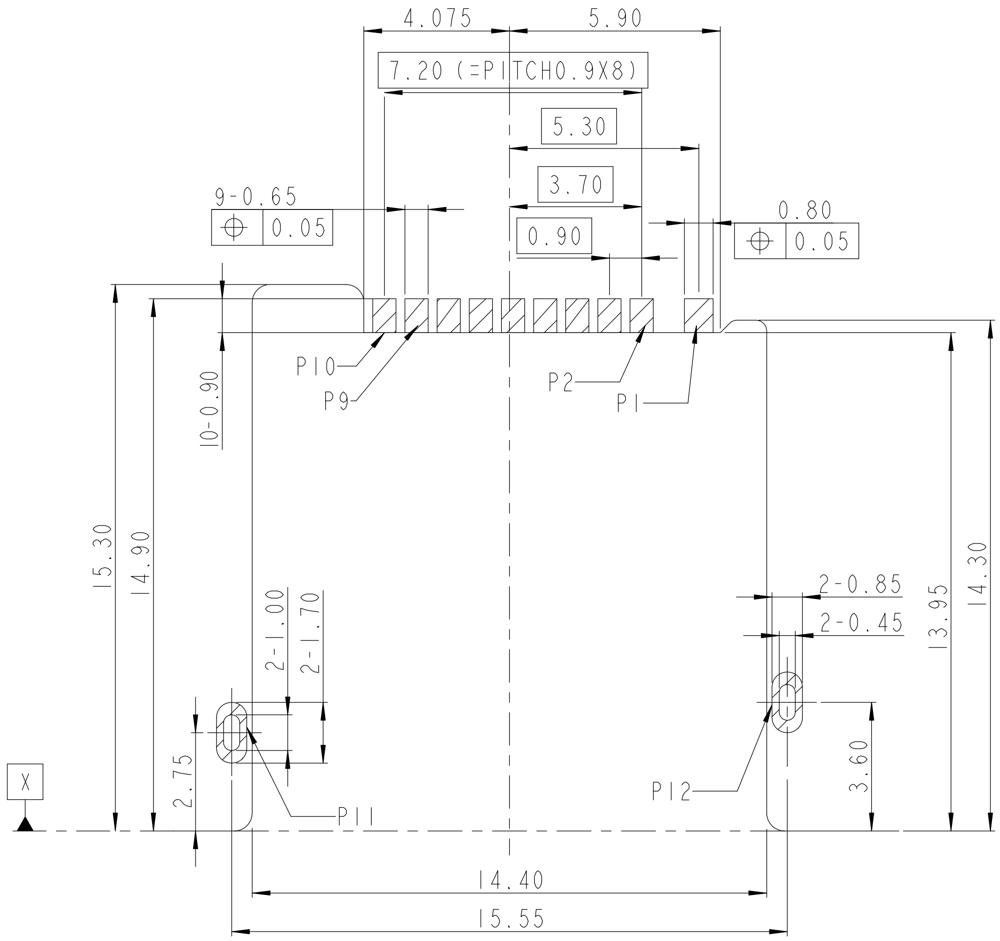
REV.	ECN.NO.	MODIFY.CONTENT



Recommended P.C.B LAYOUT

BOTTOM VIEW(CONNECTOR) (TOLERANCE+/-0.05)

TOP VIEW(SYSTEM)

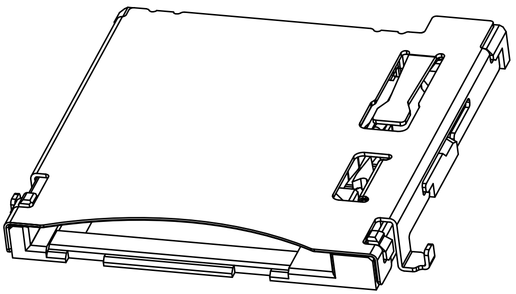
▨ : PAD AREA

NOTES :

1. MATERIAL :
   - 1.1 HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
   - 1.2 SHELL: STAINLESS STEEL SUS304.
   - 1.3 CONTACT: COPPER ALLOY C5210.

2. FINISH :
   - 2.1 CONTACT: GOLD PLATING ON CONTACT AREA, GOLD FLASH ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
   - 2.2 SHELL: 30u" MIN NICKEL PLATING OVERALL.

3. EIECTRICAL CHARACTERISTICS:
   - 3.1 OPERATING VOLTAGE : 100V AC(rms)/DC.
   - 3.2 CURRENT RATING : 0.5 A.
   - 3.3 OPERATING TEMPERATURE: −25°C~+85°C.
   - 3.4 CONTACT RESISTANCE: 100 m OHMS MAX.
   - 3.5 INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
   - 3.6 DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

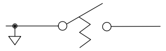
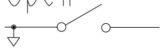
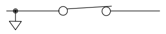


PART.NO.:
MR198-AP401-**

08: 功能区镀金1U",锡脚Gold Flash
09: 功能区镀金3U",锡脚Gold Flash
10: 功能区镀金5U",锡脚Gold Flash
11: 功能区镀金15U",锡脚Gold Flash
12: 功能区镀金30U",锡脚Gold Flash

Pin No.	Pin Assignment
P1	MICRO SD CD
P2	MICRO SD DAT1
P3	MICRO SD DAT0
P4	MICRO SD VSS
P5	MICRO SD CLK
P6	MICRO SD VDD
P7	MICRO SD CMD
P8	MICRO SD CD/DAT3
P9	MICRO SD DAT2
P10	GND
P11	GND
P12	GND

Opening/Close of Switch

	Card Detect Switch	
Card Uninsertion	Open	
Card Half Insertion	Open	
Card Insertion	Close	
N/O  P1 P4	Open  P1 P4	Close  P1 P4

GENERAL	TOLERANCE	DWG.NO.	MR198-AP401-00
x.±0.50	x.°± 5°	REV.	A
.x±0.25	.x°± 2°	SIZE	
.xx±0.15	.xx°± 1°	A4	

PART.NO.	MR198-AP401-✱✱	DRAWN	L.M.J 2019.07.19
TITLE	Micro SD Push反向沉板2.03 conn.	CHECKED	
SHEET	2 OF 3	APPROVED	

UNIT	mm	SCALE	1:1

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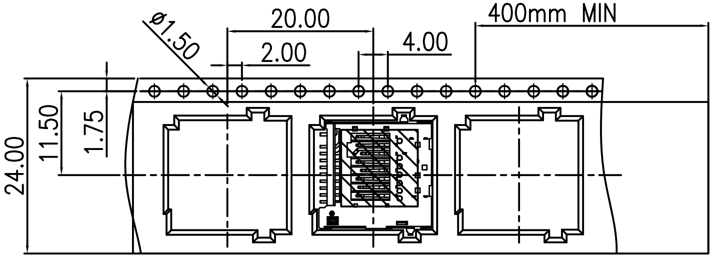
包裝作業規範

包裝作業圖示及說明　(PACKING OPERATION DIAGRAM & INSTRUCTION)

一.

1) 將成品一一放入REEL包裝盤內,依同一方向放入 .

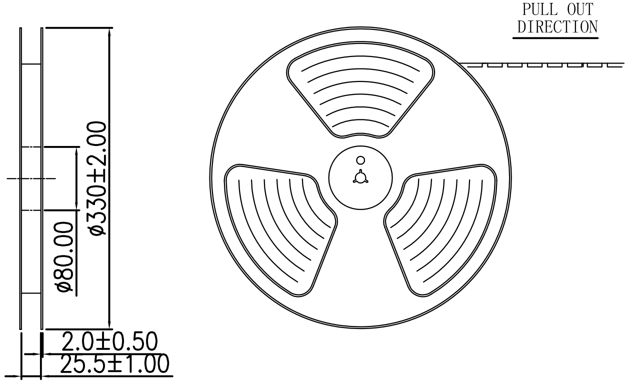
2) 包裝時,如下圖所示,放置 1000 個成品 .



二.

1)裝盘前先把前面空15pcs产品,然后再开始装盘,
尾端也需空出15pcs产品,上带加长200mm。

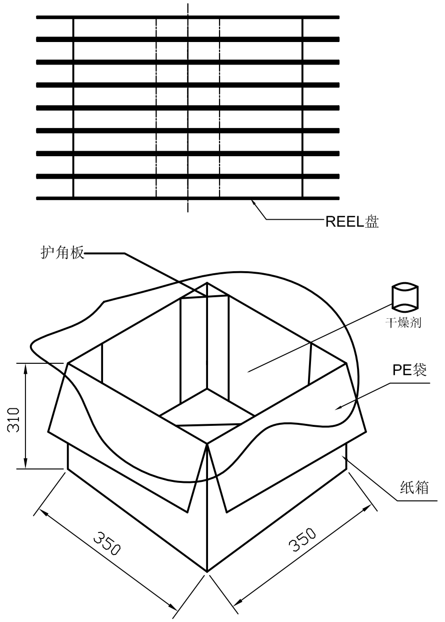
2)装满成品的REEL包装盘如下图所示。



三.

1) 每箱裝 10 盘REEL包裝盤 .

2) 每箱放置10000PCS 的成品 .



四.

1) 用TAPE將紙箱封實 .

備　註　(REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿 .

GENERAL	TOLERANCE	DWG.NO.	MR198-AP401-00	PART.NO.	MR198-AP401-✱✱	DRAWN	L.M.J 2019.07.19	UNIT	mm	SCALE	1:1
x.±0.50	x.°± 5°	REV.	A	TITLE	Micro SD Push反向沉板2.03 conn.	CHECKED					
.x±0.25	.x°± 2°	SIZE		SHEET	3 OF 3	APPROVED					
.xx±0.15	.xx°± 1°	A4									

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